

Power Schottky rectifier

Features

- High junction temperature capability
- Avalanche rated
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- High frequency operation

Description

Dual centre tab Schottky rectifier suited for high frequency switch mode power supply.

Packaged in TO-220FPAB, TO-220AB, TO-247, I²PAK, and D²PAK, this device is intended to be used in notebook and LCD adaptors and desktop SMPS. In these applications the STPS30H60C provides a good margin between the remaining voltages applied on the diode and the voltage capability of the diode.

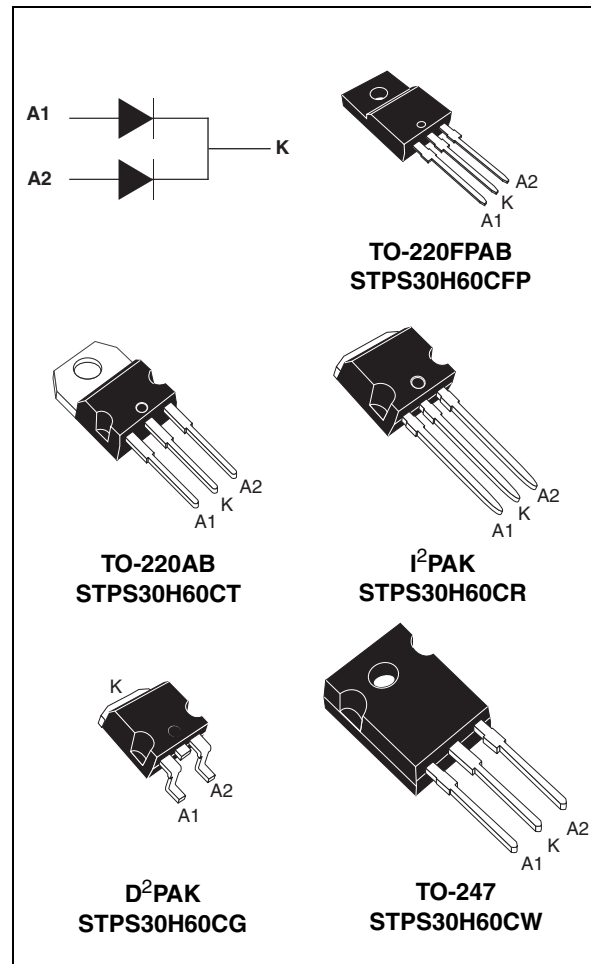


Table 1. Device summary

| Symbol | Value |
|-------------|----------|
| $I_{F(AV)}$ | 2 X 15 A |
| V_{RRM} | 60 V |
| T_j | 175 °C |
| V_F (typ) | 0.535 V |

1 Characteristics

Table 2. Absolute ratings (limiting values per diode)

| Symbol | Parameter | | Value | Unit | |
|---------------------|---|---------------------------------------|----------------------------|----------|---|
| V _{RRM} | Repetitive peak reverse voltage | | 60 | V | |
| I _{F(RMS)} | Forward rms current | | 30 | A | |
| I _{F(AV)} | Average forward current, δ = 0.5 | TO-220AB T _c = 155 °C | Per diode Total package | 15 30 | A |
| | | TO-220FPAB T _c = 125 °C | Per diode | 15 | |
| | | TO-220FPAB T _c = 90 °C | Total package | 30 | |
| I _{FSM} | Surge non repetitive forward current | t _p = 10 ms sinusoidal | 230 | A | |
| P _{ARM} | Relative peak avalanche power | T _j = 25 °C | t _p = 1 μs | 10 200 | W |
| T _{stg} | Storage temperature range | | -65 to + 175 | °C | |
| T _j | Maximum operating junction temperature ⁽¹⁾ | | 175 | °C | |

1. $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal parameters

| Symbol | Parameter | | Value | Unit | |
|----------------------|------------------|--|-----------|------|------|
| R _{th(j-c)} | Junction to case | TO-220AB, I ² PAK, D ² PAK, TO-247 | Per diode | 1.5 | °C/W |
| | | | Total | 0.8 | |
| | | TO-220FPAB | Per diode | 4.7 | |
| | | | Total | 3.95 | |
| R _{th(c)} | Coupling | TO-220AB, I ² PAK, D ² PAK, TO-247 | 0.1 | | |
| | | TO-220FPAB | 3.2 | | |

Table 4. Static electrical characteristics

| Symbol | Parameter | Test conditions | | Min. | Typ. | Max. | Unit |
|-------------------------------|-------------------------|-------------------------|-----------------------------------|------|------|------|------|
| I _R ⁽¹⁾ | Reverse leakage current | T _j = 25 °C | V _R = V _{RRM} | | | 60 | μA |
| | | T _j = 125 °C | | | 8 | 25 | mA |
| V _F ⁽²⁾ | Forward voltage drop | T _j = 25 °C | I _F = 7.5 A | | | 550 | mV |
| | | T _j = 125 °C | | | 435 | 470 | |
| | | T _j = 25 °C | I _F = 15 A | | | 660 | |
| | | T _j = 125 °C | | | 535 | 570 | |
| | | T _j = 25 °C | I _F = 30 A | | | 820 | |
| | | T _j = 125 °C | | | 635 | 690 | |

1. Pulse test: t_p = 5 ms, δ < 2%

2. Pulse test: t_p = 380 μs, δ < 2%

To evaluate the conduction losses use the following equation: $P = 0.45 \times I_{F(AV)} + 0.008 \times I_{F(RMS)}^2$

Figure 1. Conduction losses versus average forward current

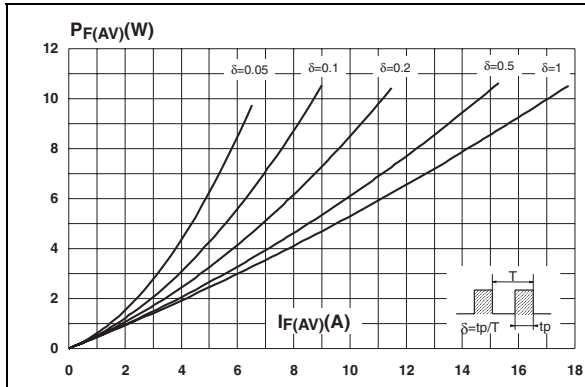


Figure 2. Average forward current versus ambient temperature ($\delta = 0.5$, per diode)

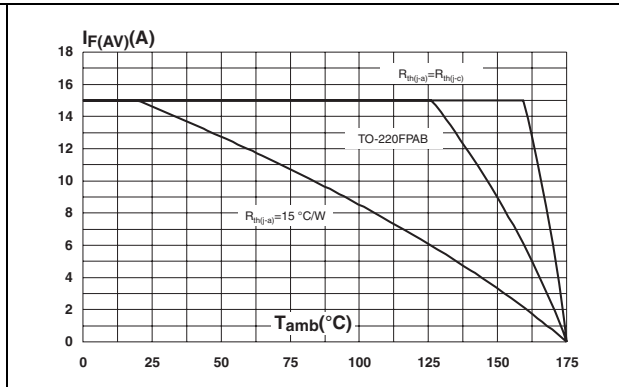


Figure 3. Normalized avalanche power derating versus pulse duration

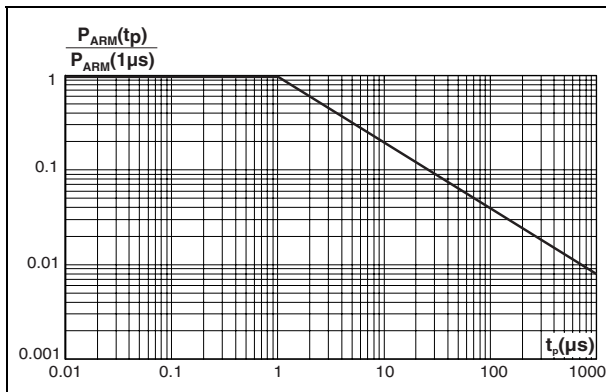


Figure 4. Normalized avalanche power derating versus junction temperature

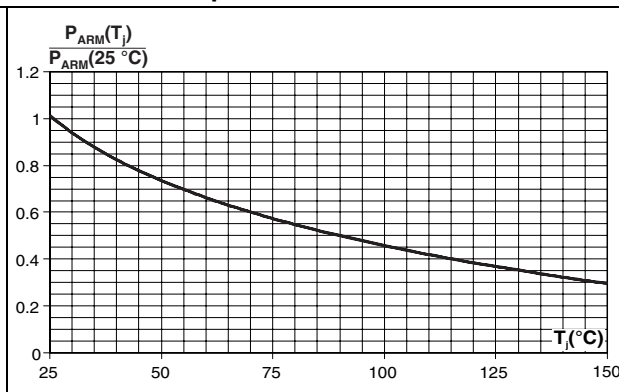


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

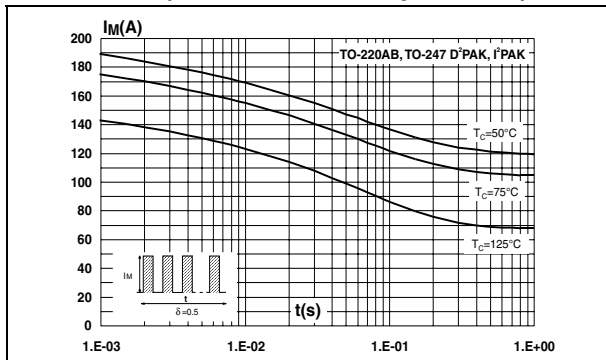


Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

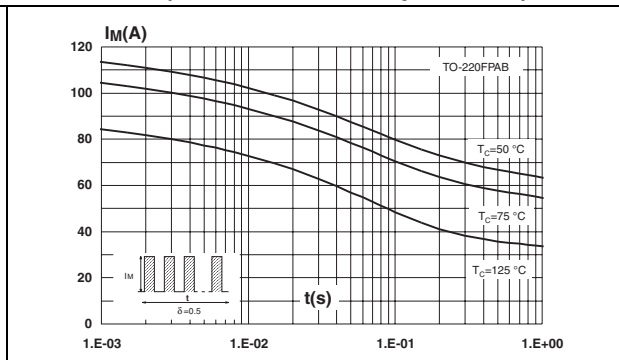


Figure 7. Relative variation of thermal impedance junction to case versus pulse duration

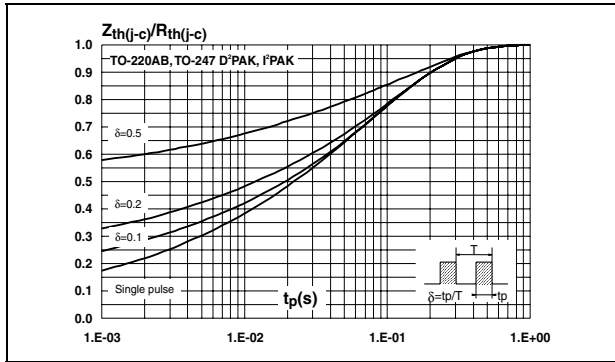


Figure 8. Relative variation of thermal impedance junction to case versus pulse duration

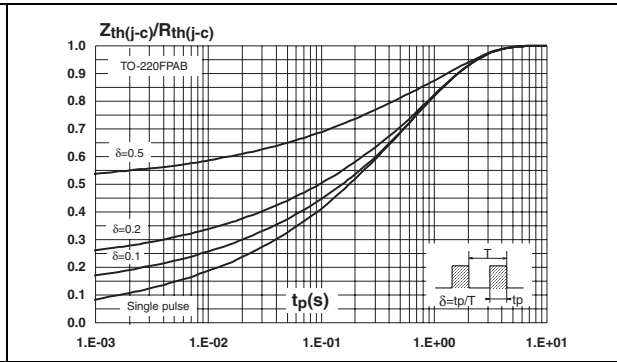


Figure 9. Reverse leakage current versus reverse voltage applied (typical values, per diode)

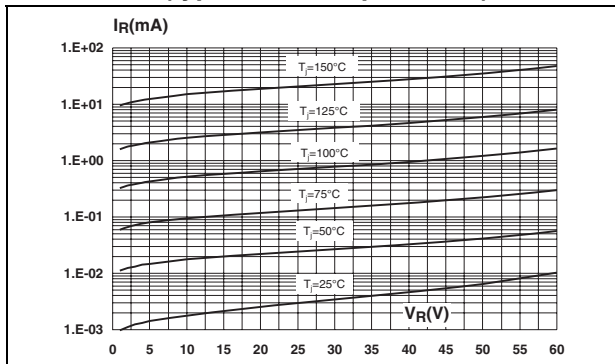


Figure 10. Junction capacitance versus reverse voltage applied (typical values, per diode)

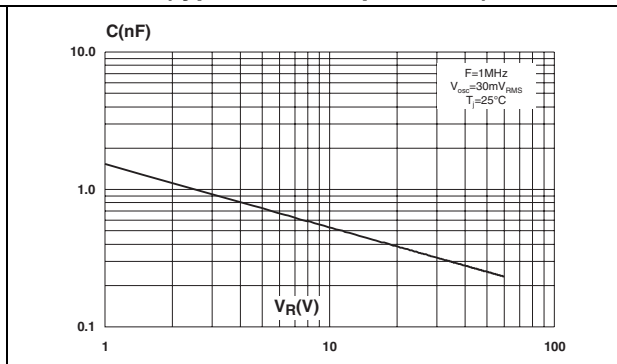


Figure 11. Forward voltage drop versus forward current (per diode)

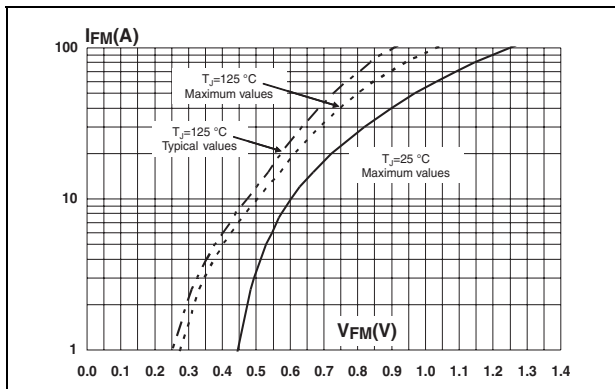
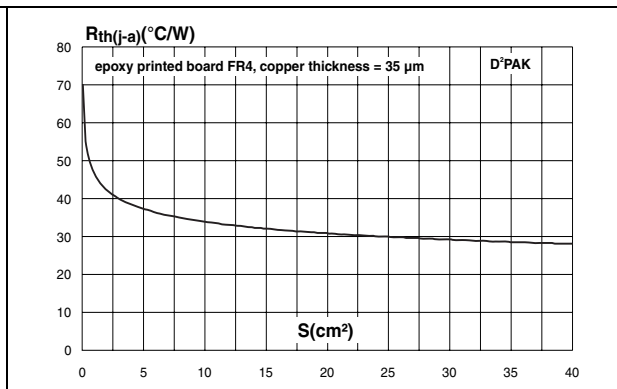


Figure 12. Thermal resistance junction to ambient versus copper surface under tab



2 Package information

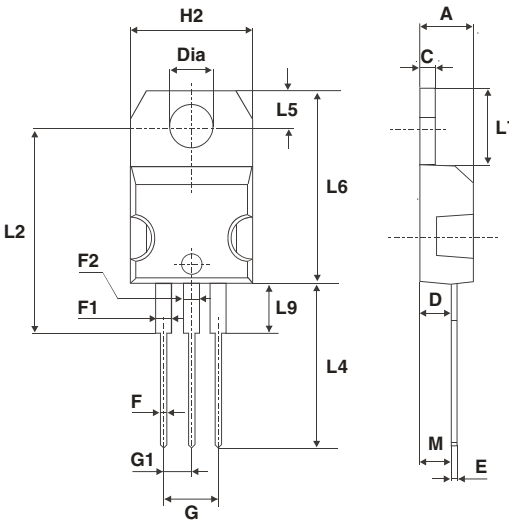
- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque values:
 - TO-220FPAB and TO-220AB 0.4 to 0.6 N·m
 - TO-247 0.9 to 1.2 N·m

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Table 5. TO-220FPAB dimensions

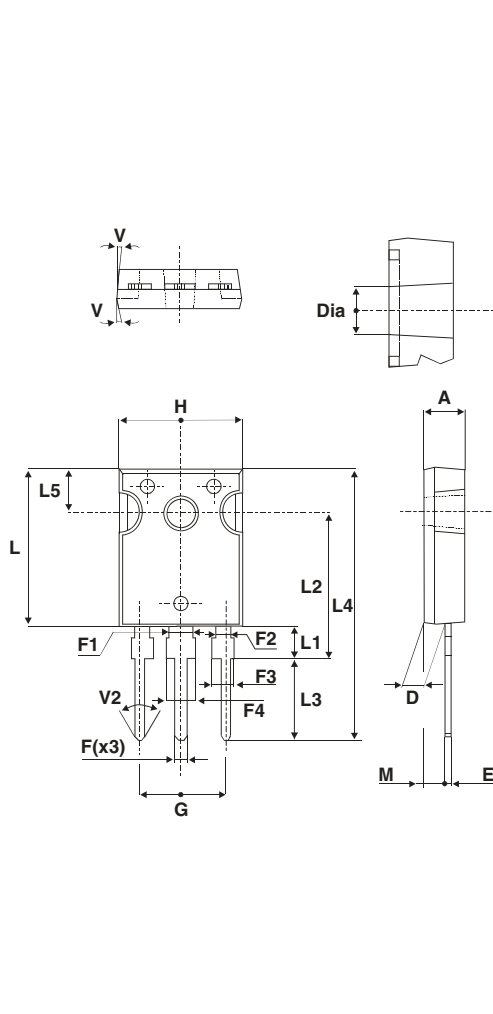
| Ref. | Dimensions | | | |
|------|-------------|------|-----------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 4.4 | 4.6 | 0.173 | 0.181 |
| B | 2.5 | 2.7 | 0.098 | 0.106 |
| D | 2.5 | 2.75 | 0.098 | 0.108 |
| E | 0.45 | 0.70 | 0.018 | 0.027 |
| F | 0.75 | 1 | 0.030 | 0.039 |
| F1 | 1.15 | 1.70 | 0.045 | 0.067 |
| F2 | 1.15 | 1.70 | 0.045 | 0.067 |
| G | 4.95 | 5.20 | 0.195 | 0.205 |
| G1 | 2.4 | 2.7 | 0.094 | 0.106 |
| H | 10 | 10.4 | 0.393 | 0.409 |
| L2 | 16 Typ. | | 0.63 Typ. | |
| L3 | 28.6 | 30.6 | 1.126 | 1.205 |
| L4 | 9.8 | 10.6 | 0.386 | 0.417 |
| L5 | 2.9 | 3.6 | 0.114 | 0.142 |
| L6 | 15.9 | 16.4 | 0.626 | 0.646 |
| L7 | 9.00 | 9.30 | 0.354 | 0.366 |
| Dia. | 3.00 | 3.20 | 0.118 | 0.126 |

Table 6. TO-220AB dimensions



| Ref | Dimensions | | | |
|-------|-------------|-------|------------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 4.40 | 4.60 | 0.173 | 0.181 |
| C | 1.23 | 1.32 | 0.048 | 0.051 |
| D | 2.40 | 2.72 | 0.094 | 0.107 |
| E | 0.49 | 0.70 | 0.019 | 0.027 |
| F | 0.61 | 0.88 | 0.024 | 0.034 |
| F1 | 1.14 | 1.70 | 0.044 | 0.066 |
| F2 | 1.14 | 1.70 | 0.044 | 0.066 |
| G | 4.95 | 5.15 | 0.194 | 0.202 |
| G1 | 2.40 | 2.70 | 0.094 | 0.106 |
| H2 | 10 | 10.40 | 0.393 | 0.409 |
| L2 | 16.4 typ. | | 0.645 typ. | |
| L4 | 13 | 14 | 0.511 | 0.551 |
| L5 | 2.65 | 2.95 | 0.104 | 0.116 |
| L6 | 15.25 | 15.75 | 0.600 | 0.620 |
| L7 | 6.20 | 6.60 | 0.244 | 0.259 |
| L9 | 3.50 | 3.93 | 0.137 | 0.154 |
| M | 2.6 typ. | | 0.102 typ. | |
| Diam. | 3.75 | 3.85 | 0.147 | 0.151 |

Table 7. TO-247 dimensions



| Ref | Dimensions | | | | | |
|------|-------------|-------|-------|--------|-------|-------|
| | Millimeters | | | Inches | | |
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 4.85 | | 5.15 | 0.191 | | 0.203 |
| D | 2.20 | | 2.60 | 0.086 | | 0.102 |
| E | 0.40 | | 0.80 | 0.015 | | 0.031 |
| F | 1.00 | | 1.40 | 0.039 | | 0.055 |
| F1 | | 3.00 | | | 0.118 | |
| F2 | | 2.00 | | | 0.078 | |
| F3 | 2.00 | | 2.40 | 0.078 | | 0.094 |
| F4 | 3.00 | | 3.40 | 0.118 | | 0.133 |
| G | | 10.90 | | | 0.429 | |
| H | 15.45 | | 15.75 | 0.608 | | 0.620 |
| L | 19.85 | | 20.15 | 0.781 | | 0.793 |
| L1 | 3.70 | | 4.30 | 0.145 | | 0.169 |
| L2 | | 18.50 | | | 0.728 | |
| L3 | 14.20 | | 14.80 | 0.559 | | 0.582 |
| L4 | | 34.60 | | | 1.362 | |
| L5 | | 5.50 | | | 0.216 | |
| M | 2.00 | | 3.00 | 0.078 | | 0.118 |
| V | | 5° | | | 5° | |
| V2 | | 60° | | | 60° | |
| Dia. | 3.55 | | 3.65 | 0.139 | | 0.143 |

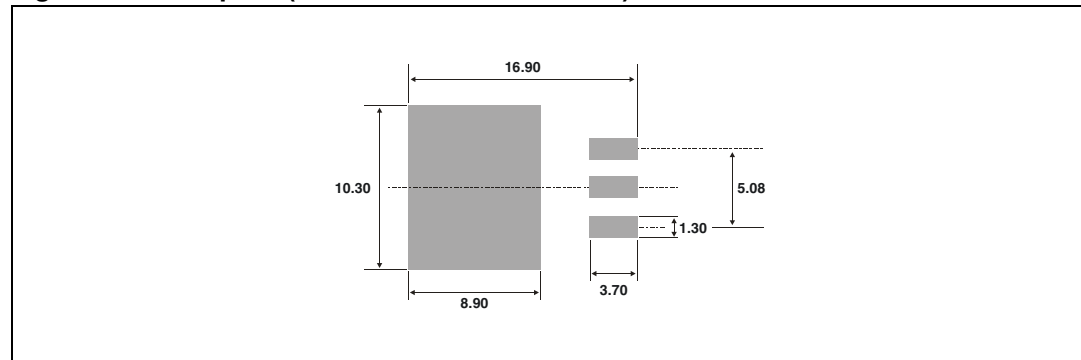
Table 8. I²PAK dimensions

| Ref. | Dimensions | | | |
|------|-------------|-------|--------|-------|
| | Millimeters | | Inches | |
| | Min. | Max. | Min. | Max. |
| A | 4.40 | 4.60 | 0.173 | 0.181 |
| A1 | 2.40 | 2.72 | 0.094 | 0.107 |
| b | 0.61 | 0.88 | 0.024 | 0.035 |
| b1 | 1.14 | 1.70 | 0.044 | 0.067 |
| c | 0.49 | 0.70 | 0.019 | 0.028 |
| c2 | 1.23 | 1.32 | 0.048 | 0.052 |
| D | 8.95 | 9.35 | 0.352 | 0.368 |
| e | 2.40 | 2.70 | 0.094 | 0.106 |
| e1 | 4.95 | 5.15 | 0.195 | 0.203 |
| E | 10 | 10.40 | 0.394 | 0.409 |
| L | 13 | 14 | 0.512 | 0.551 |
| L1 | 3.50 | 3.93 | 0.138 | 0.155 |
| L2 | 1.27 | 1.40 | 0.050 | 0.055 |

Table 9. D²PAK dimensions

| Ref. | Dimensions | | | |
|------|-------------|-------|------------|-------|
| | Millimeters | | Inches | |
| | Min. | Max | Min. | Max. |
| A | 4.40 | 4.60 | 0.173 | 0.181 |
| A1 | 2.49 | 2.69 | 0.098 | 0.106 |
| A2 | 0.03 | 0.23 | 0.001 | 0.009 |
| B | 0.70 | 0.93 | 0.027 | 0.037 |
| B2 | 1.14 | 1.70 | 0.045 | 0.067 |
| C | 0.45 | 0.60 | 0.017 | 0.024 |
| C2 | 1.23 | 1.36 | 0.048 | 0.054 |
| D | 8.95 | 9.35 | 0.352 | 0.368 |
| E | 10.00 | 10.40 | 0.393 | 0.409 |
| G | 4.88 | 5.28 | 0.192 | 0.208 |
| L | 15.00 | 15.85 | 0.590 | 0.624 |
| L2 | 1.27 | 1.40 | 0.050 | 0.055 |
| L3 | 1.40 | 1.75 | 0.055 | 0.069 |
| M | 2.40 | 3.20 | 0.094 | 0.126 |
| R | 0.40 typ. | | 0.016 typ. | |
| V2 | 0° | 8° | 0° | 8° |

Figure 13. Footprint (dimensions in millimeters)



3 Ordering information

Table 10. Ordering information

| Order code | Marking | Package | Weight | Base qty | Delivery mode |
|----------------|----------------|--------------------|--------|----------|---------------|
| STPS30H60CT | STPS30H60CT | TO-220AB | 2.23 g | 50 | Tube |
| STPS30H60CR | STPS30H60CR | I ² PAK | 1.49 g | 50 | Tube |
| STPS30H60CG | STPS30H60CG | D ² PAK | 1.48 g | 50 | Tube |
| STPS30H60CG-TR | STPS30H60CG-TR | D ² PAK | 1.48 g | 1000 | Tape and reel |
| STPS30H60CW | STPS30H60W | TO-247 | 4.46 g | 30 | Tube |
| STPS30H60CFP | STPS30H60CFP | TO-220FPAB | 2.00 g | 50 | Tube |

4 Revision history

Table 11. Document revision history

| Date | Revision | Changes |
|-------------|----------|--|
| 27-Feb-2006 | 1 | First issue. |
| 31-Mar-2007 | 2 | Added TO-220FPAB package. Updated thermal parameters in Table 2. |
| 08-Jul-2011 | 3 | Updated Table 2 . |

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